

Electronic Patent Application Fee Transmittal

Application Number:	10597066			
Filing Date:	10-Jul-2006			
Title of Invention:	METHOD OF FORMING THIN SGOI WAFERS WITH HIGH RELAXATION AND LOW STACKING FAULT DEFECT DENSITY			
First Named Inventor/Applicant Name:	Huajie Chen			
Filer:	Yuanmin Cai/Maureen DiDonato			
Attorney Docket Number:	FIS920030342US1			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Application for patent term adjustment	1455	1	200	200
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				200